

N24UT1610-H

List

List.....1

Package outline.....2

Features.....2

Applications.....2

Mechanical data.....2

Maximum ratings2

Electrical characteristics.....2

Typical performance characteristics.....3

Pinning information.....4

Marking information.....4

Suggested solder pad layout.....4

Package Information.....5

Reel packing.....6

Suggested thermal profiles for soldering processes.....6

High reliability test capabilities.....7

N24UT1610-H

2800W Uni-directional TVS For ESD Protection : 24V

Features

- Peak pulse current : 80A ($t_p=8/20\mu s$).
- Protects one I/O line.
- Provide transient protection:
IEC 61000-4-2 (ESD) Contact $\pm 30KV$ /Air $\pm 30KV$
IEC 61000-4-4 (EFT) 40A (5/50ns)
- We declare that the material of product compliance with RoHS requirements.

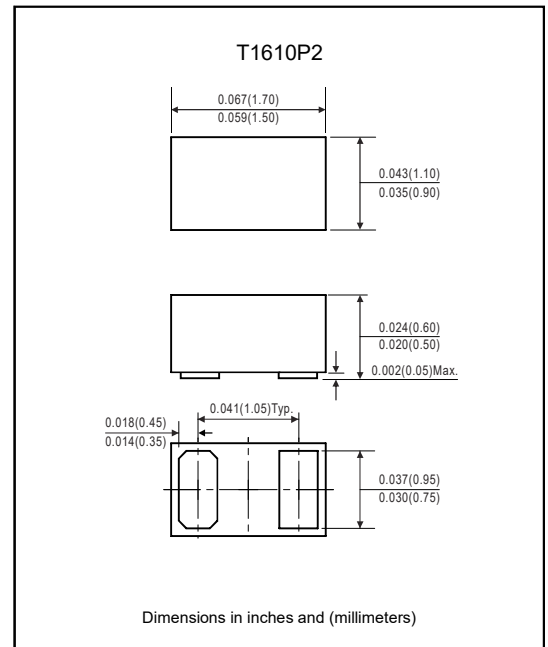
Applications

- Cellular Handsets and accessories.
- Digital Visual Interface (DVI).
- Display ports.
- MDDI port.

Mechanical data

- Case : Molded plastic, T1610P2.
- Flammability rating : UL94V-0.
- Weight : Approximated 2.5 mg.

Package outline



Maximum ratings (At $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power ($t_p=8/20\mu s$)	P_{PP}	2800	W
Peak pulse current ($t_p=8/20\mu s$)	I_{PP}	80	A
Electrostatic discharge voltage (IEC61000-4-2 Contact & Air)	V_{ESD}	± 30	KV
Operating temperature range	T_J	+125	$^\circ C$
Storage temperature	T_{STG}	-55 to +150	$^\circ C$
Lead soldering temperature (10 sec.)	T_L	260	$^\circ C$

Electrical characteristics (At $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse stand-off voltage	V_{RWM}				24	V
Breakdown voltage	V_{RWM}	$I_T = 1mA$	26.5		32.5	V
Reverse leakage current	I_R	$V_{RWM} = 24V$			0.5	μA
Forward voltage	V_F	$I_F = 10mA$		1.0	1.2	V
Clamping voltage ($t_p = 8/20\mu s$)	V_C	$I_{PP} = 1A$		33		V
		$I_{PP} = 80A$		35		
Junction capacitance	C_{ESD}	$V_R=0V, f=1MHz$		260		pF

N24UT1610-H

Typical performance characteristics

FIG1: Power rating derating curve

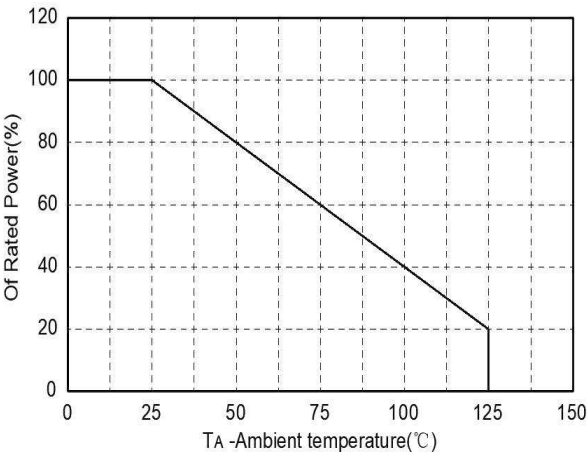


FIG2: pulse Waveform

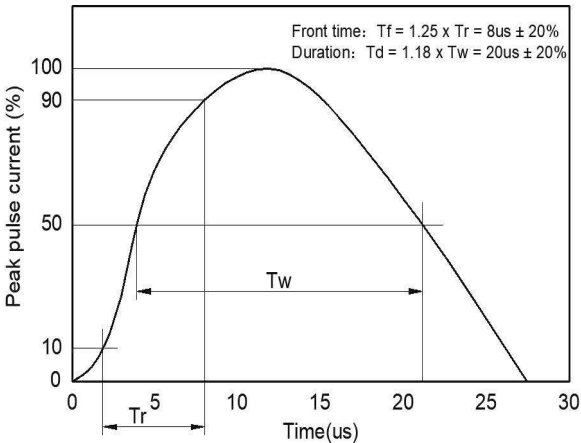


FIG3: Capacitance between teminals charateristics

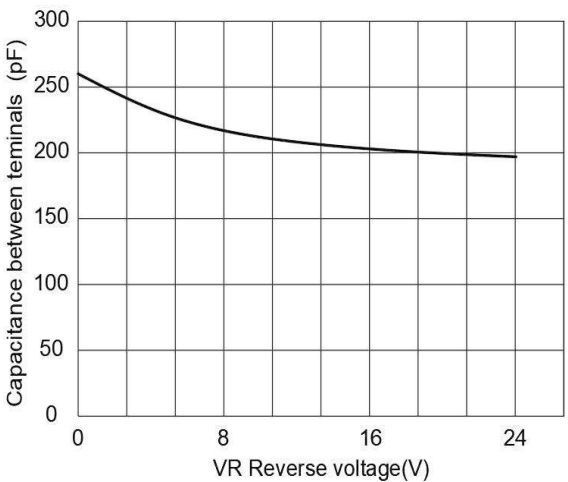
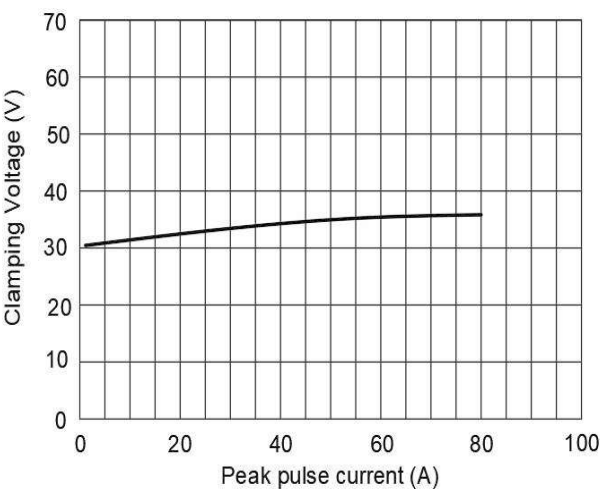
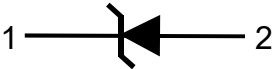


FIG4: Clamping Voltage vs. Peak Pulse Current



N24UT1610-H

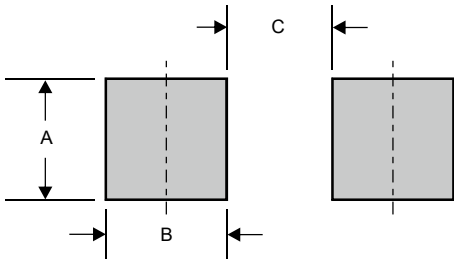
Pinning information

Pin	Simplified outline	Symbol
Pin1 Cathode Pin2 Anode		

Marking

Type number	Marking code
N24UT1610-H	24P

Suggested solder pad layout

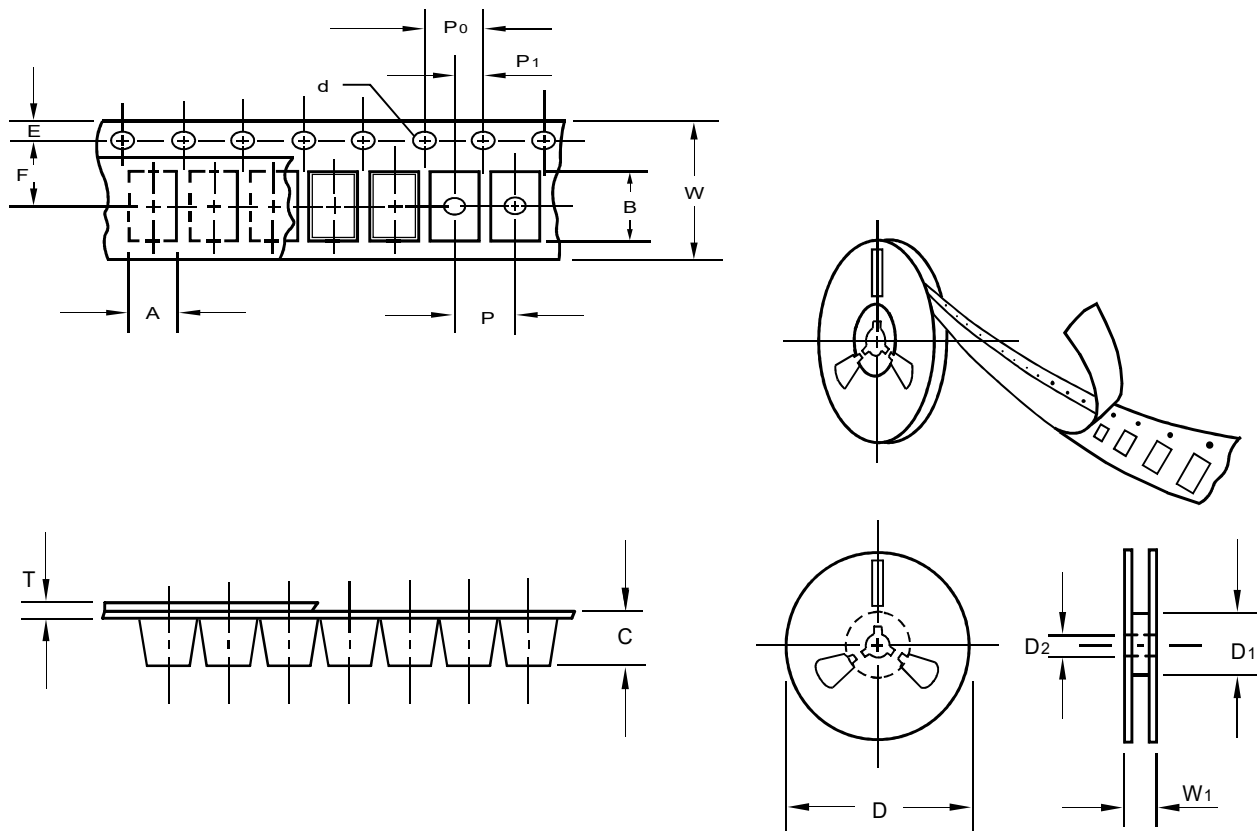


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
T1610P2	0.039 (1.00)	0.025 (0.625)	0.024 (0.60)

N24UT1610-H

Packing information



unit:mm

Item	Symbol	Tolerance	T1610P2
Carrier width	A	0.1	1.15
Carrier length	B	0.1	1.80
Carrier depth	C	0.1	0.63
Sprocket hole	d	0.1	1.55
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	50.00
Feed hole diameter	D2	0.2	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	2.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.20
Tape width	W	0.3	8.00
Reel width	W1	1.0	9.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

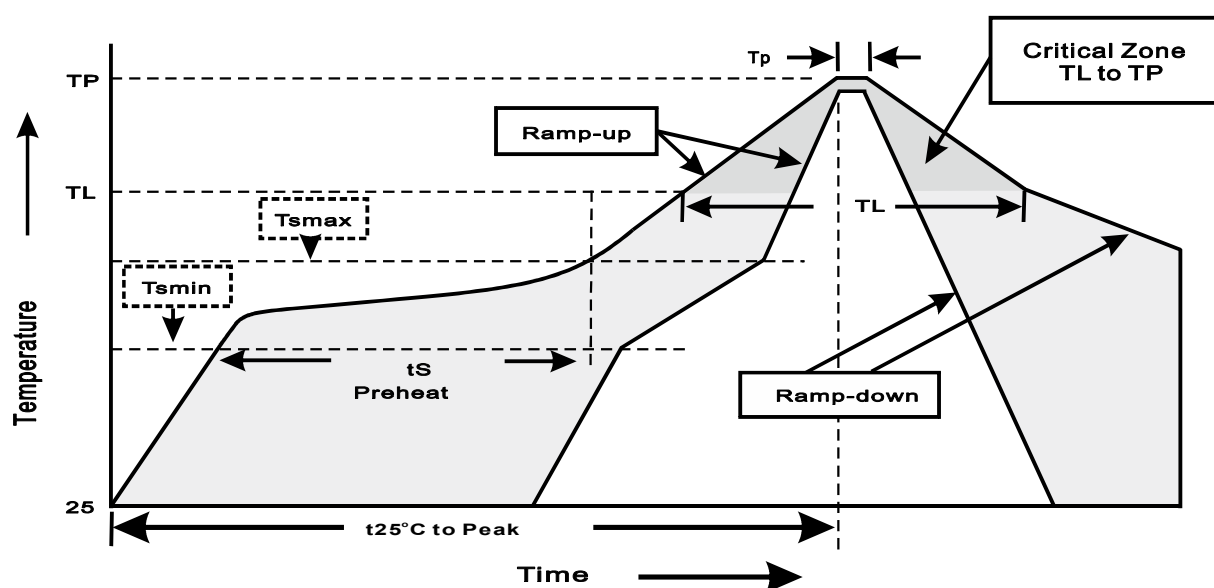
N24UT1610-H

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
T1610P2	7"	3,000	4.0	30,000	183*123*183	178	382*257*387	240,000	9.6

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smin}) -Temperature Max(T _{smax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

N24UT1610-H

High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec.	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_{BR} = V_{BR} \text{ Min} * 80\%$ at $T_J = 150^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Pressure Cooker	15P _{SIG} at $T_A = 121^\circ\text{C}$ for 4 hrs.	JESD22-A102
5. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
6. Humidity	at $T_A = 85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
7. High Temperature Storage Life	at 150°C for 1000 hrs.	MIL-STD-750D METHOD-1031